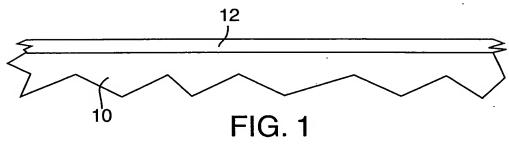
Agarwal et al.

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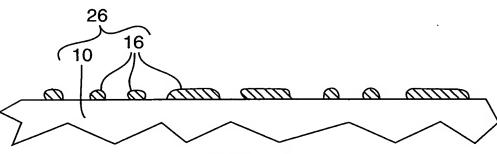


FIG. 2

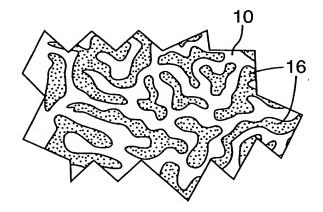
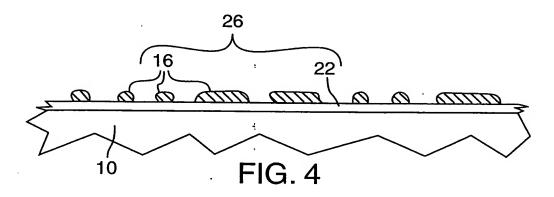
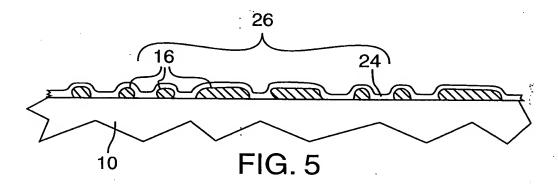


FIG. 3

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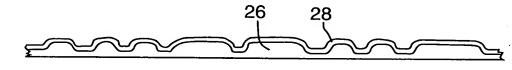


FIG. 6

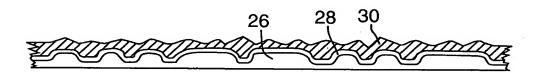


FIG. 7

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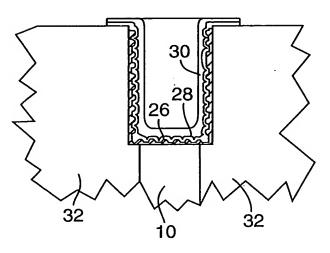


FIG. 8A

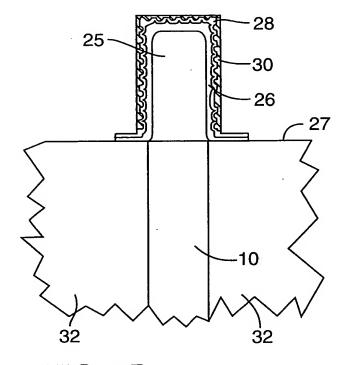


FIG. 8B

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